

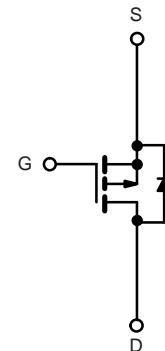
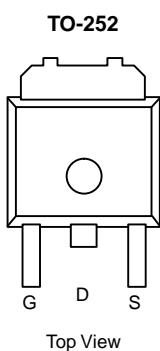
50P03L-VB Datasheet

P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^a
- 30	0.011 at $V_{GS} = - 10$ V	- 60
	0.013 at $V_{GS} = - 4.5$ V	- 55

FEATURES

- Compliant to RoHS Directive 2002/95/EC



ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)			
Parameter	Symbol	Limit	Unit
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_J = 175$ °C)	I_D	- 60 ^a	A
		- 45	
Pulsed Drain Current	I_{DM}	- 240	
Avalanche Current	I_{AR}	- 50	
Repetitive Avalanche Energy ^b	E_{AR}	180	mJ
Power Dissipation	P_D	127 ^d	W
		3.75	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient	R_{thJA}	40	°C/W
PCB Mount (TO-263) ^c		62.5	
Junction-to-Case	R_{thJC}	0.8	

Notes:

- a. Package limited.
- b. Duty cycle ≤ 1 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. See SOA curve for voltage derating.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

SPECIFICATIONS ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}$, $I_D = -250 \mu\text{A}$	- 30			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = -250 \mu\text{A}$	- 1		- 3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}$, $V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -30 \text{ V}$, $V_{GS} = 0 \text{ V}$			- 1	
		$V_{DS} = -30 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 125^\circ\text{C}$			- 50	μA
		$V_{DS} = -30 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 175^\circ\text{C}$			- 250	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} = -5 \text{ V}$, $V_{GS} = -10 \text{ V}$	- 120			A
Drain-Source On-State Resistance ^a	$R_{DS(\text{on})}$	$V_{GS} = -10 \text{ V}$, $I_D = -30 \text{ A}$		0.011		
		$V_{GS} = -10 \text{ V}$, $I_D = -30 \text{ A}$, $T_J = 125^\circ\text{C}$		0.015		Ω
		$V_{GS} = -10 \text{ V}$, $I_D = -30 \text{ A}$, $T_J = 175^\circ\text{C}$		0.019		
		$V_{GS} = -4.5 \text{ V}$, $I_D = -20 \text{ A}$		0.013		
Forward Transconductance ^a	g_{fs}	$V_{DS} = -15 \text{ V}$, $I_D = -75 \text{ A}$	20			S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$, $V_{DS} = -25 \text{ V}$, $f = 1 \text{ MHz}$		3300		
Output Capacitance	C_{oss}			1565		pF
Reversen Transfer Capacitance	C_{rss}			715		
Total Gate Charge ^c	Q_g	$V_{DS} = -15 \text{ V}$, $V_{GS} = -10 \text{ V}$, $I_D = -75 \text{ A}$		160	240	
Gate-Source Charge ^c	Q_{gs}			32		nC
Gate-Drain Charge ^c	Q_{gd}			30		
Turn-On Delay Time ^c	$t_{d(\text{on})}$			25	40	
Rise Time ^c	t_r	$V_{DD} = -15 \text{ V}$, $R_L = 0.2 \Omega$ $I_D \geq -75 \text{ A}$, $V_{GEN} = -10 \text{ V}$, $R_g = 2.5 \Omega$		225	360	
Turn-Off Delay Time ^c	$t_{d(\text{off})}$			150	240	
Fall Time ^c	t_f			210	340	
Source-Drain Diode Ratings and Characteristics^b ($T_C = 25^\circ\text{C}$)						
Continuous Current	I_S				- 60	
Pulsed Current	I_{SM}				- 240	A
Forward Voltage ^a	V_{SD}	$I_F = -75 \text{ A}$, $V_{GS} = 0 \text{ V}$		- 1.2	- 1.5	V
Reverse Recovery Time	t_{rr}	$I_F = -75 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$		55	100	ns
Peak Reverse Recovery Current	$I_{RM(\text{REC})}$			2.5	5	A
Reverse Recovery Charge	Q_{rr}			0.07	0.25	μC

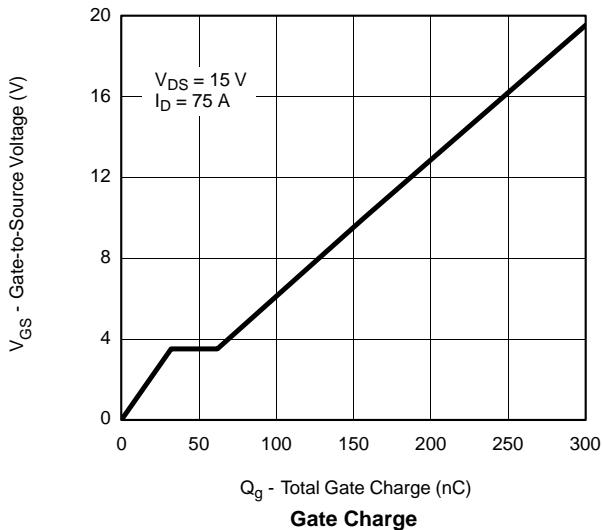
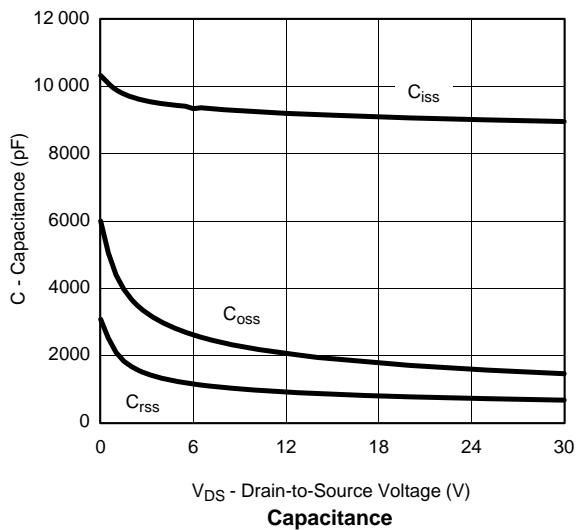
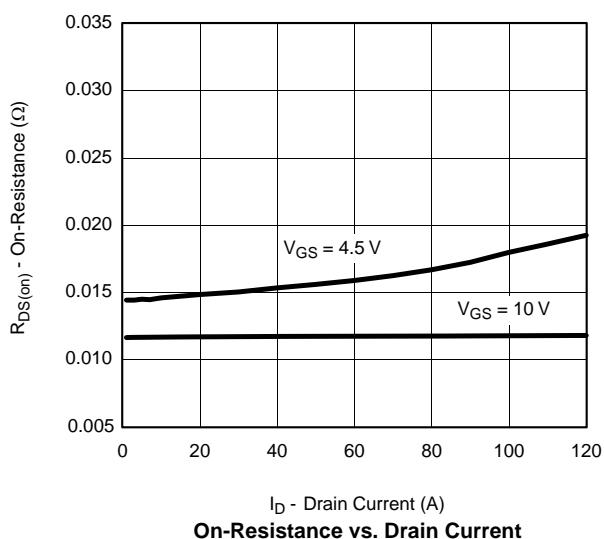
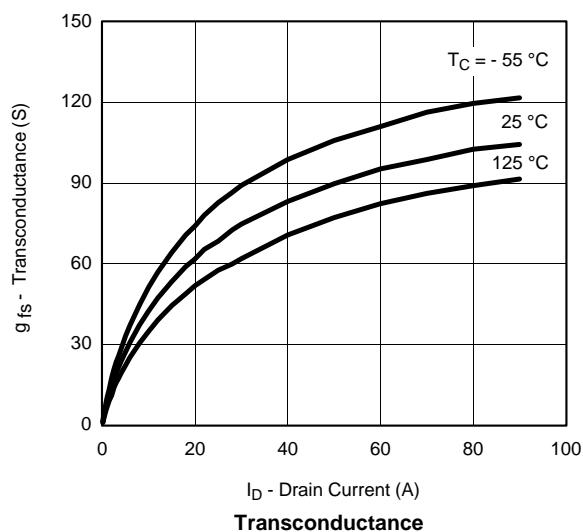
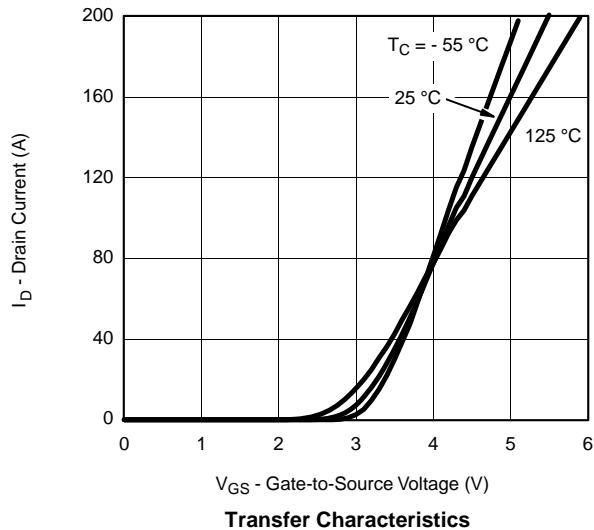
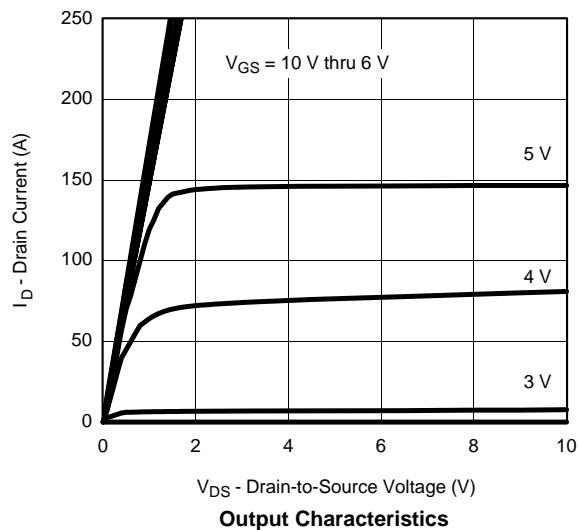
Notes:

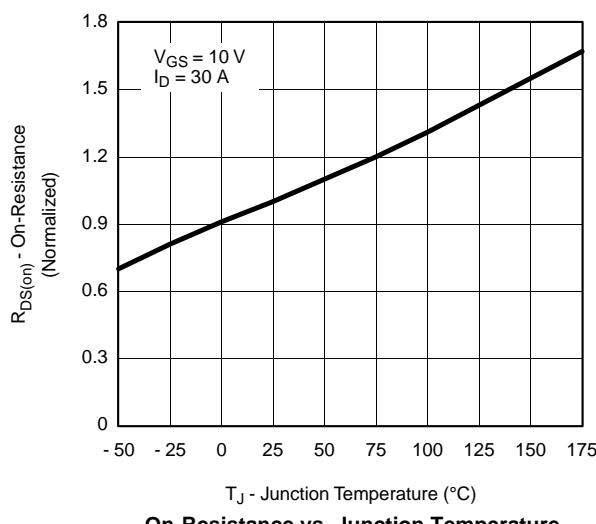
a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

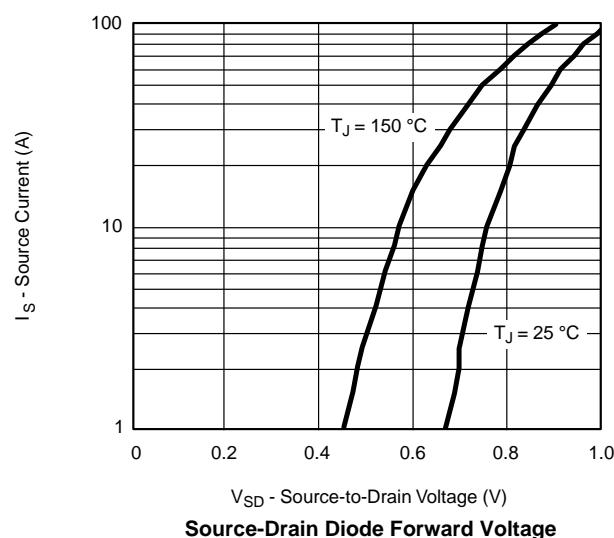
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

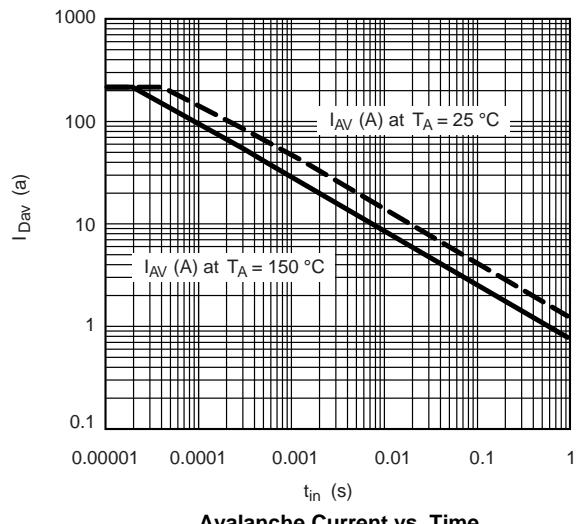
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


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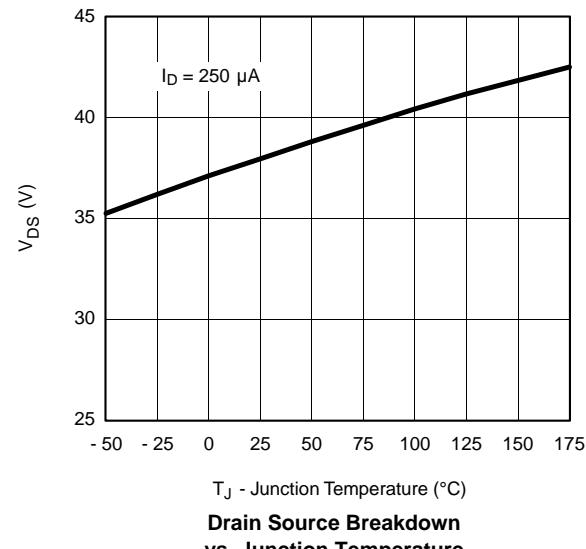
On-Resistance vs. Junction Temperature



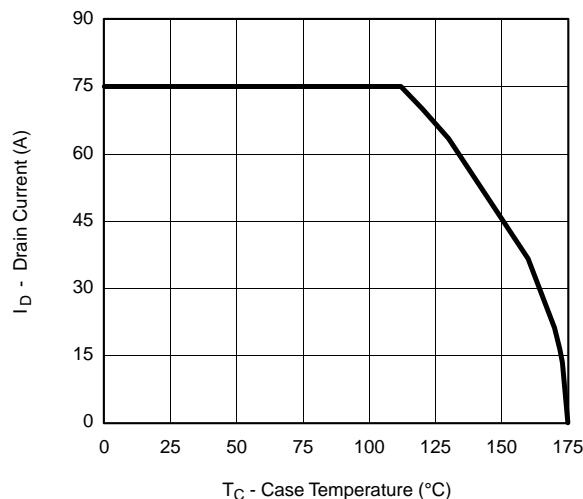
Source-Drain Diode Forward Voltage



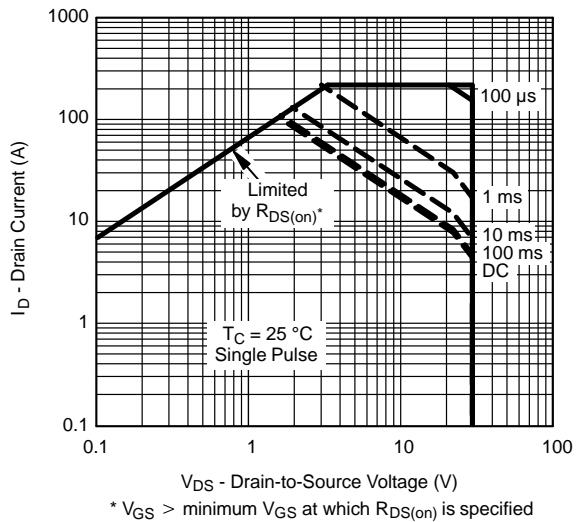
Avalanche Current vs. Time

Drain Source Breakdown
vs. Junction Temperature

THERMAL RATINGS

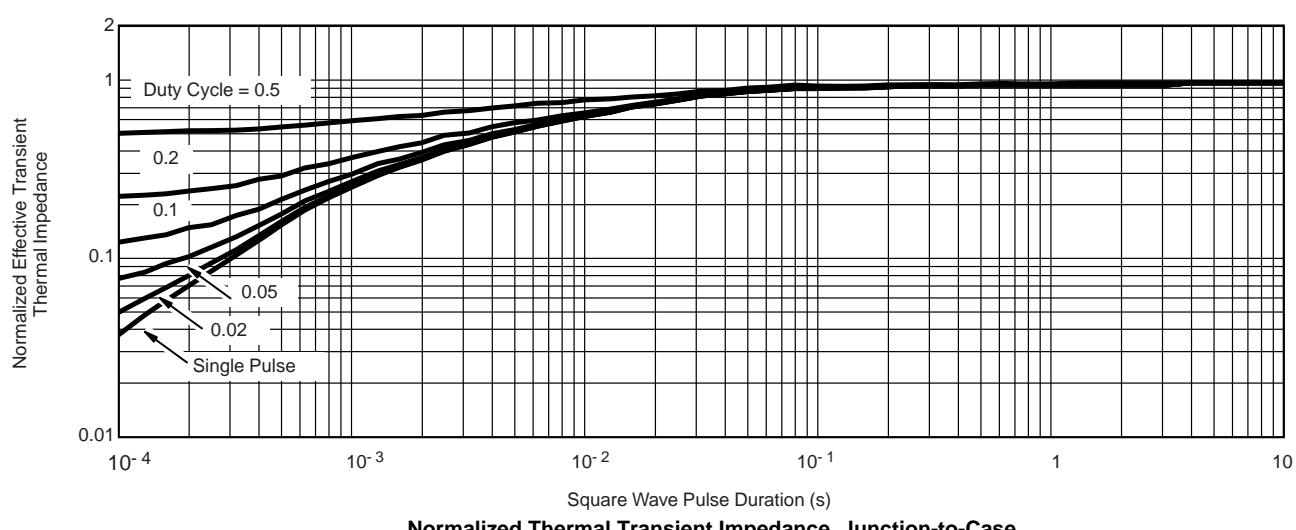


Maximum Avalanche and Drain Current
vs. Case Temperature



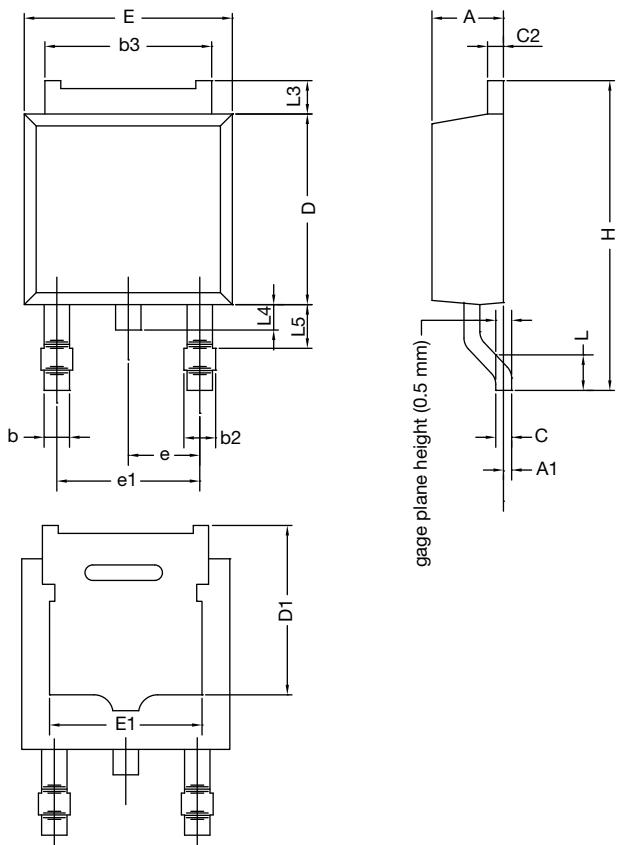
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

TO-252AA CASE OUTLINE



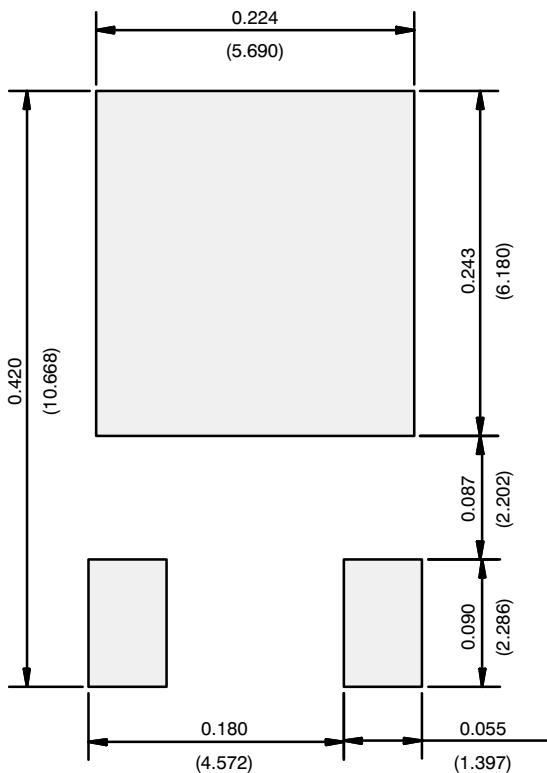
DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
C	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	5.21	-	0.205	-
E	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
H	9.40	10.41	0.370	0.410
e	2.28 BSC		0.090 BSC	
e1	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.14	1.52	0.045	0.060

ECN: X12-0247-Rev. M, 24-Dec-12
 DWG: 5347

Note

- Dimension L3 is for reference only.

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads
Dimensions in Inches/(mm)

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